



MoU signed to bring substrate manufacturing technology to India; Govt. of Odisha, Intel and 3DGS parties to the agreement

Investments by leading global semiconductor players is a recognition of government's efforts in this sector, reflect industry's trust in India: Ashwini Vaishnaw

One of the largest high-technology manufacturing investments in India, the project builds on the efforts under the India Semiconductor Mission

Posted On: 29 MAY 2026 4:24PM by PIB Delhi

Union Minister of Electronics & IT, Ashwini Vaishnaw; along with Chief Minister of Odisha, Mohan Charan Majhi; CEO, Intel, Lip-Bu Tan, and other dignitaries, witnessed the signing of an MoU to bring substrate manufacturing technology to India.

Congratulations to the Govt. of Odisha, Intel and 3DGS on signing an MoU to bring substrate manufacturing technology to India.

This will further advance semiconductor ecosystem in India. pic.twitter.com/elxs6r8muN

— Ashwini Vaishnaw (@AshwiniVaishnaw) May 29, 2026

The MoU has been signed between the Government of Odisha, Intel Corporation and 3DGS Inc. USA for a framework to establish an Advanced Packaging Glass Core Substrate Manufacturing Facility in Odisha. The project represents one of the largest high-technology manufacturing investments in the country. The facility is proposed to be located in the Bhubaneswar–Khurda region.

Union Minister for Electronics & IT stressed that signing of the landmark MoU is in line with the Government's vision of developing the entire ecosystem of semiconductor manufacturing in India. He said that the entry of firms like Applied Materials Inc., Lam Research, Tokyo Electron Ltd., Merck Electronics, and signing of the MoU between Tata Electronics and Dutch multinational ASML – is a recognition of the Government's efforts in the semiconductor sector and the trust the industry places in India.

The proposed project would be implemented in phases over a period of five-six years. It is expected to generate direct high-skilled employment opportunities while creating significant indirect employment across the broader manufacturing and technology ecosystem.

The facility will focus on advanced packaging glass core substrates, high-density interconnect substrates and associated semiconductor technologies, with Intel supporting technology know-how and process expertise. It is expected to contribute to capability development, ecosystem growth and export-oriented manufacturing in India.

The initiative builds on the ongoing efforts under the India Semiconductor Mission to strengthen domestic manufacturing, design ecosystem and supply chain capabilities. It is expected to position Odisha among emerging global centres for semiconductor manufacturing and digital infrastructure.

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(Release ID: 2266614) Visitor Counter : 858

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